

# EDCON-COMPONENTS



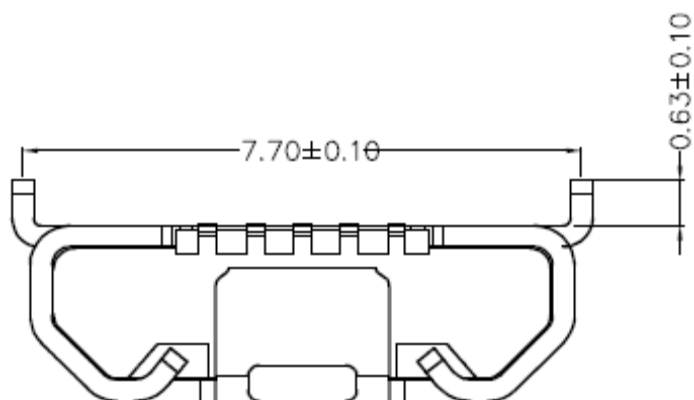
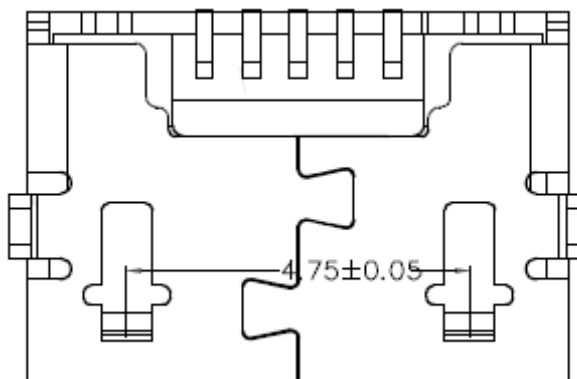
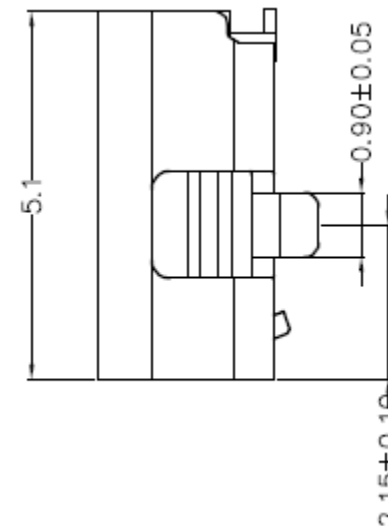
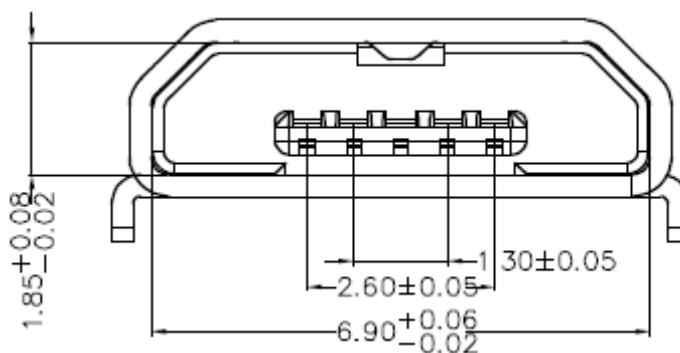
## Specifications

Voltage Rating: 30 VAC  
 Current Rating: 1,0A max f. Pin 1,5  
 Operating Temperature: - 55°C to + 85°C  
 Contact Resistance: 30m Ohm max.  
 Withstanding Voltage: 100VAC min.  
 Insulation Resistance: >100M Ohm min.  
 Contact Thickness: 0,15mm

### Material:

Insulator : look order code  
 Color: look order code  
 Contact Material: look order code  
 Contact Type: Stamped  
 Contact Plating: look order code  
 Shielding: look order code  
 Lifetime: 6000 cycles min.  
 Force: 35Newton

## Drawing ( dimensions all into mm)



**SMT Micro USB Connector Type B Offset Type 2 DIP Shell No Post w. Curl**

Part No.: **T64073**

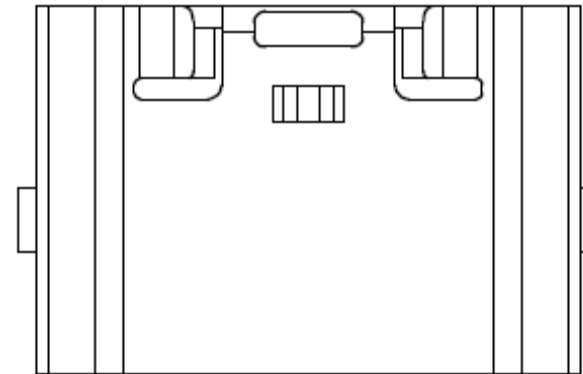
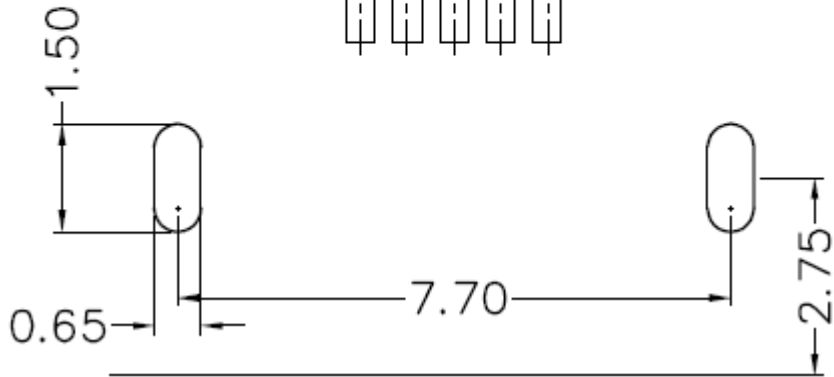
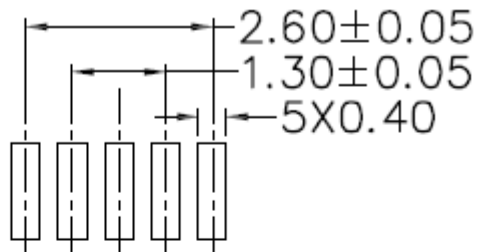
DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	15.08.2015
APPD:	Schumi			FINISH	Jamy		Sheet No.	1 from 4	Customer:

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PCB Layout



**SMT Micro USB Connector Type B Offset Type 2 DIP Shell No Post w. Curl**

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# EDCON-COMPONENTS



## Ordering Informations

Serie	Color Inside	Shell Material	Insulator Material	Contact Material	Contact Plating	Special function	Packing	Packing		
<b>T64073</b>	<b>BK</b>	<b>B</b>	<b>P</b>	<b>B</b>	<b>G0</b>	<b>0</b>	<b>R</b>	<b>BU</b>		

<b>BK</b> = Black Color	<b>B</b> = Brass	<b>P</b> = PBT + 30% GF	<b>B</b> = Brass	<b>G0</b> = Gold Flash (Standard)	<b>0</b> = No Special function	<b>R</b> = ROHS conform <b>N</b> = NON ROHS conform	<b>BU</b> = Bulk Ware
<b>WH</b> = White Color	<b>I</b> = Iron	<b>L</b> = LCP	<b>P</b> = Phosphor Copper	<b>G1</b> = 3μ Gold			<b>TR</b> = Tape / Reel w. Pic and Place Foil
	<b>S</b> = Stainless Steel			<b>G1</b> = 5μ Gold			
				<b>G1</b> = 10μ Gold			
				<b>G1</b> = 15μ Gold			
				<b>G1</b> = 30μ Gold			
						<b>IV</b> = Individual Packing	

**PIC and PLACE FOIL** for automatic assembly machine



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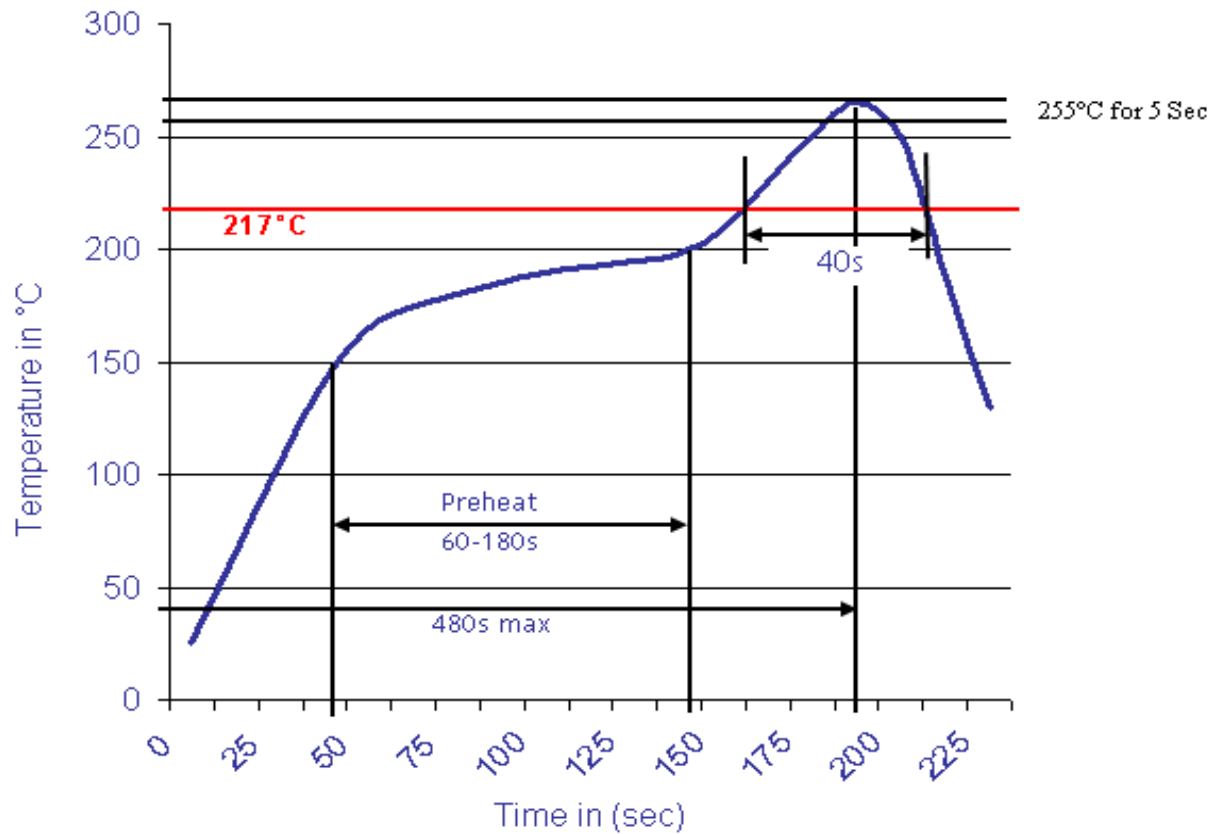
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Soldering Profile Curve

Classification Reflow Profile (JEDEC J-STD-020C)



**SMT Micro USB Connector**  
**Type B Offset Type 2 DIP**  
**Shell No Post w. Curl**  
 Part No.: **T64073**

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